

ABSTRACT

A method of manufacturing a semiconductor device, comprises providing a wiring substrate having a main surface, an insulating film formed on the main surface, and electrodes formed on the main surface so as to be exposed from the insulating film. A semiconductor chip is adhesively fixed to the insulating film. Conductive wires connect the electrodes on the main surface of the wiring substrate and electrodes on the chip. A groove is formed between the chip and the electrodes on the substrate. A protruding portion of the adhesive stays within the groove and does not reach the electrodes on the substrate.